

# Bill of Materials

TI DESIGNS, TIDA-00197

Designator	Description	Manufacturer	MFG Part Number	Quantity
C1	CAP ALUM 220UF 50V 20% SMD	Nichicon	UWT1H221MNL1GS	1
C12, C13	CAP CER 1UF 50V 10% X5R 0603	Taiyo Yuden	UMK107BJ105KA-T	2
C14, C17	CAP CER 1000PF 50V 10% X7R 0603	Kemet	C0603C102K5RACTU	2
C15	CAP CER 4.7UF 6.3V 10% X5R 0603	Taiyo Yuden	JMK107BJ475KA-T	1
C2, C3, C4, C5, C6, C7, C8, C9, C10, C11	CAP CER 0.1UF 50V 10% X7R 0603	Yageo	CC0603KRX7R9BB104	10
D1	TVS DIODE 28.2VWM 45.7VC SMD	Littelfuse	P6SMB33A	1
N/A	MACHINE SCREW PAN PHILLIPS M2	B&F Fastener Supply	MPMS 002 0005 PH	3
N/A	BRUSHLESS DC MOTOR ENCLOSURE	Shenzhen Hengdrive Electric	B6020S (without PCB)	1
P1	CONN HEADER 2POS STR .100" GOLD	3M	929647-01-02-EU	1
R13, R14	RES 143K OHM 1/10W 1% 0603 SMD	Yageo	RC0603FR-07143KL	2
R15	RES 1M OHM 1/8W .1% 0805 SMD	Panasonic	ERA-6AEB105V	1
R16	RES 523K OHM 1/10W 1% 0603 SMD	Yageo	RC0603FR-07523KL	1
R17	RES 3.92 OHM 1/10W 1% 0603 SMD	Yageo	RC0603FR-073R92L	1
R18, R19, R20	RES 0.0 OHM 1/10W JUMP 0603 SMD	Yageo	RC0603JR-070RL	3
R10, R11, R12	RES 3.0K OHM 1/10W 5% 0603 SMD	Yageo	RC0603JR-073KL	3
R3, R4, R5, R6, R7	RES 0.24 OHM 1/4W 5% 0805	TE Connectivity	RLP73N2AR24JTD	5
R2, R8, R9	RES 15.0K OHM 1/10W 1% 0603 SMD	Yageo	RC0603FR-0715KL	3
U1	IC CTRLR DC MOTOR 40VQFN	Texas Instruments	DRV8308RHAT	1
U2, U3, U4	HALL SENSOR LATCH	Texas Instruments	DRV5013ADQDBZR	3
U5, U6, U7	MOSFET N-CH 60V DUAL 8SOIC	Texas Instruments	CSD88537ND	3
U8	IC OSC SILICON 1MHZ TSOT23-6	Linear Technology	LTC6992IS6-2#TRMPBF	1

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